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DEPFET:

- Previous problems are gone. The data looks pretty similar to the data they get in Germany. Doing tests with different sources. Trying to disentangle the noise pixels in order to obtain a “cleaner” S/N characterization.
- Matrix doesn't still work properly with Vgate negative. Munich people say that this is not a problem. The only drawback about this problem is that it may not suit properly for developing the LV system.
- Still working in trying to understand the data.
- Still software related problems with the DEPFET data analysis. No success yet in trying to install the software properly.

Thinning of 3d double-sided detectors:

- Production already started for 100um, 150um and 200um 256x256 matrix and 55um pixel size. The first run will be done for the 200um thick sensors and will be plugged to a TimePix device (provided by Glasgow) and assembled into a TimePix PCB provided by the CERN MediPix group. The sensor to chip bump-bonding will be performed at the CNM. The time scale for this first run is 2-3 weeks.

Beam injection in LHCb:

- The detector needs to be run safely, so for the first beam injection the ST will be off.